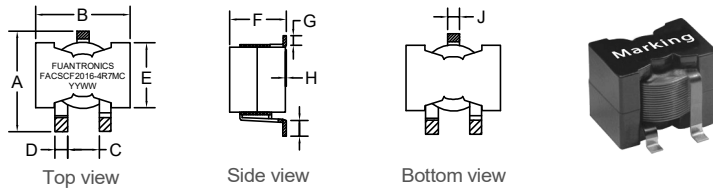


P/N: FACSCF2016-4R7MC

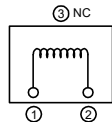


Outline Dimensions(Unit:mm)

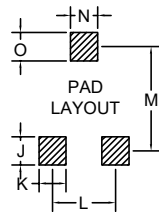


A	B	C	D	E	F	G	H	I	J
Max	Max	±0.60	±0.20	±0.50	Max	REF		±0.50	REF
22.5	21.8	7.00	2.50	14.0	16.5	2.00	0-0.15	2.50	2.50

Electronical Schematic



Suggested Pad layout



J	5.00 REF
K	5.00 REF
L	9.50 REF
M	19.3 REF
N	5.00 REF
O	5.00 REF

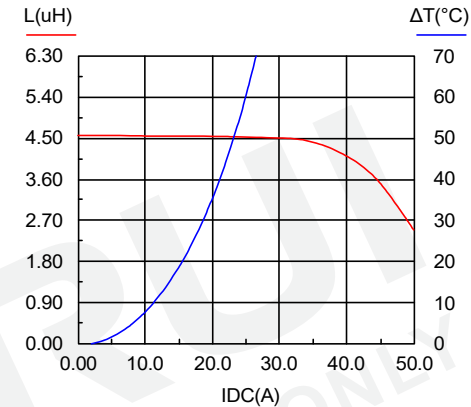
- ***Assemblage design, sturdy structure.
- ***High inductance, high current, low magnetic loss, low ESR, small parasitic capacitance.
- ***Flat wire winding, achieve a low D.C. Resistance.
- ***Temperature rise current and saturation current is less influenced by environment.

Electrical Characteristics(@25°C)

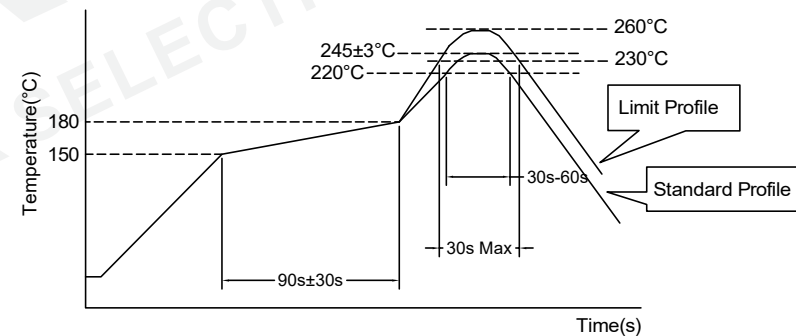
Inductance 100KHz,0.1V	DC Resistor	Saturated current 42A	Temperature rise current 21A
4.70uH±20%	4.00mΩ Max	L(42A)=80%*L0A Typ	T≤40°C Typ

- ***Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
- ***Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
- ***Operating Temperature: -40°C~+125°C.
(Temperature rise included)
- ***Storage Temperature: -40°C~+125°C.
- ***Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times